

STB6N60M2, STD6N60M2

Datasheet - production data

N-channel 600 V, 1.06 Ω typ., 4.5 A MDmesh[™] M2 Power MOSFETs in D²PAK and DPAK packages

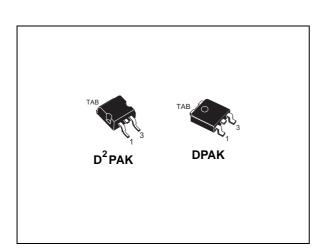
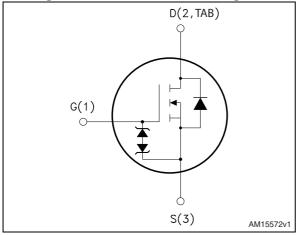


Figure 1. Internal schematic diagram



Features

Order code	V _{DS} @ T _{Jmax}	R _{DS(on)} max	Ι _D
STB6N60M2	650 V	1.2 0	4.5 A
STD6N60M2	000 V	1.2 32	т. 5 Л

- Extremely low gate charge
- Excellent output capacitance (Coss) profile
- 100% avalanche tested
- Zener-protected

Applications

• Switching applications

Description

These devices are N-channel Power MOSFETs developed using MDmesh[™] M2 technology. Thanks to their strip layout and improved vertical structure, the devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high efficiency converters.

Order code	Marking	Package	Packing
STB6N60M2	6N60M2	D ² PAK	Tape and reel
STD6N60M2	ONOOMZ	DPAK	Tape and Teel

This is information on a product in full production.

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Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
۱ _D	Drain current (continuous) at $T_C = 25 \text{ °C}$	4.5	A
۱ _D	Drain current (continuous) at $T_C = 100 \ ^{\circ}C$	2.9	A
I _{DM} ⁽¹⁾	Drain current (pulsed)	18	A
P _{TOT}	Total dissipation at $T_C = 25 \text{ °C}$	60	W
dv/dt ⁽²⁾	Peak diode recovery voltage slope	15	V/ns
dv/dt ⁽³⁾	MOSFET dv/dt ruggedness	50	V/115
T _{stg}	Storage temperature range	-55 to 150	°C
Тj	Operating junction temperature range	-55 10 150	C

Table 2. Absolute maximum ratings

1. Pulse width limited by safe operating area

Electrical ratings

2. I_{SD} \leq 4.5 A, di/dt $\,\leq$ 400 A/µs; V_{DS peak} < V_(BR)DSS, V_DD=400 V

3. $V_{DS} \le 480 \text{ V}$

Table 3. Thermal data

Symbol	Parameter	Value		Unit
Symbol	Falameter	D ² PAK	DPAK	Unit
R _{thj-case}	Thermal resistance junction-case max	2.08	3	°C/W
R _{thj-pcb}	Thermal resistance junction-pcb max ⁽¹⁾	30	50	°C/W

1. When mounted on 1 inch² FR-4, 2 Oz copper board

Table 4. Avalanche characteristics

	Symbol	Parameter	Value	Unit
I _{AR} Avalanche current, repetitive or not repetitive (pulse width limited by T _{jmax})			1	А
	E _{AS}	Single pulse avalanche energy (starting $T_j=25$ °C, $I_D=I_{AR}$; $V_{DD}=50$ V)	86	mJ



2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0	600			V
1	Zero gate voltage	V _{DS} = 600 V			1	μA
I _{DSS}	drain current ($V_{GS} = 0$)	$V_{DS} = 600 \text{ V}, \text{ T}_{C} = 125 \text{ °C}^{(1)}$			100	μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 25 V			±10	μA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 2.25 A		1.06	1.2	Ω

Table 5. On /off states

1. Defined by design, not subject to production test

Symbol	ymbol Parameter Test conditions		Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	232	-	pF
C _{oss}	Output capacitance	V _{DS} = 100 V, f = 1 MHz,	-	14	-	pF
C _{rss}	Reverse transfer capacitance	V _{GS} = 0	-	0.7	-	pF
Coss eq.(1)	Equivalent output capacitance	$V_{DS} = 0$ to 480 V, $V_{GS} = 0$	-	71	-	pF
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	6.5	-	Ω
Qg	Total gate charge	V _{DD} = 480 V, I _D = 4.5 A,	-	8.2	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 10 V	-	1.7	-	nC
Q _{gd}	Gate-drain charge	(see Figure 16)	-	4.2	-	nC

Table 6. Dynamic

1. Coss eq. is defined as a constant equivalent capacitance giving the same charging time as Coss when VDS increases from 0 to 80% VDSS

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time		-	9.5	-	ns
t _r	Rise time	V _{DD} = 300 V, I _D = 1.65 A, R _G = 4.7 Ω, V _{GS} = 10 V	-	7.4	-	ns
t _{d(off)}	Turn-off delay time	(see Figure 15 and Figure 20)	-	24	-	ns
t _f	Fall time		-	22.5	-	ns

Table 7. Switching times

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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		4.5	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		18	А
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 4.5 A, V _{GS} = 0	-		1.6	V
t _{rr}	Reverse recovery time		-	274		ns
Q _{rr}	Reverse recovery charge	I _{SD} = 4.5 A, di/dt = 100 A/μs V _{DD} = 60 V (see <i>Figure 17</i>)	-	1.47		μC
I _{RRM}	Reverse recovery current		-	10.7		А
t _{rr}	Reverse recovery time	I _{SD} = 4.5 A, di/dt = 100 A/µs	-	376		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 60 V, T _j = 150 °C	-	1.96		μC
I _{RRM}	Reverse recovery current	(see Figure 17)	-	10.5		А

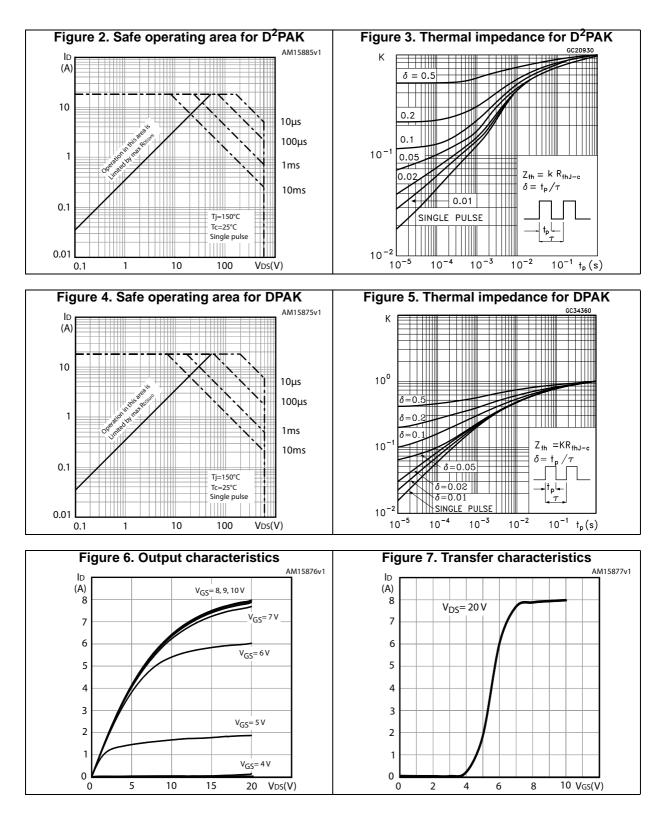
Table 8. Source drain diode

1. Pulse width limited by safe operating area.

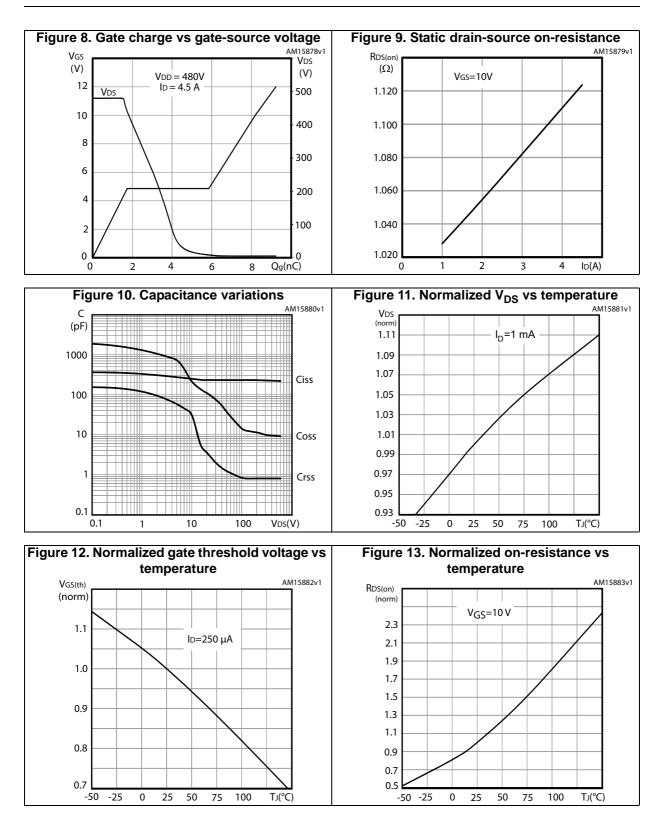
2. Pulsed: pulse duration = $300 \ \mu$ s, duty cycle 1.5%



2.1 Electrical characteristics (curves)



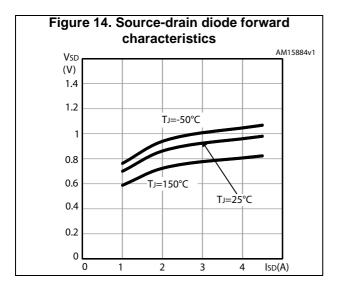




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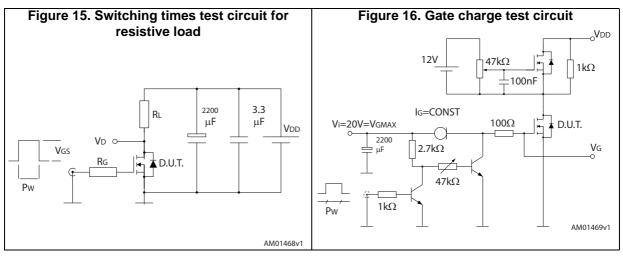
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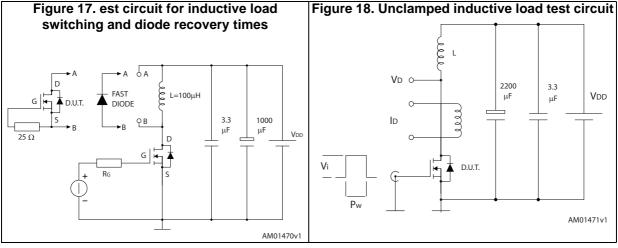
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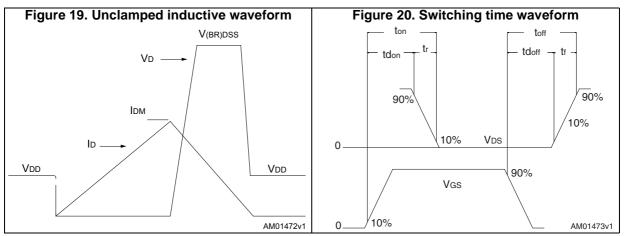




3 Test circuits









4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



4.1 D²PAK(TO-263) package information

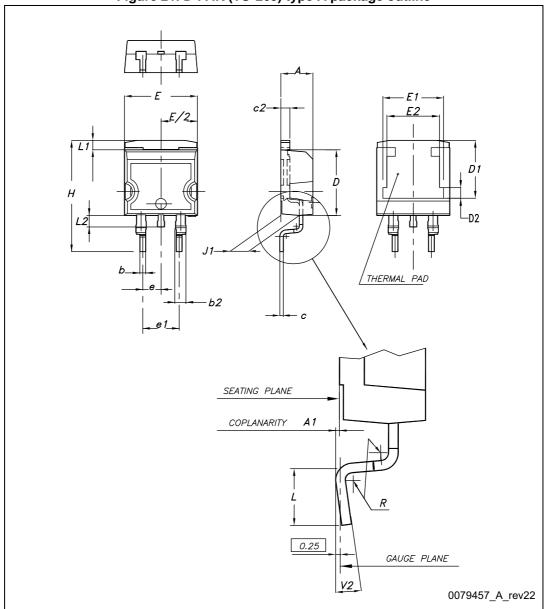


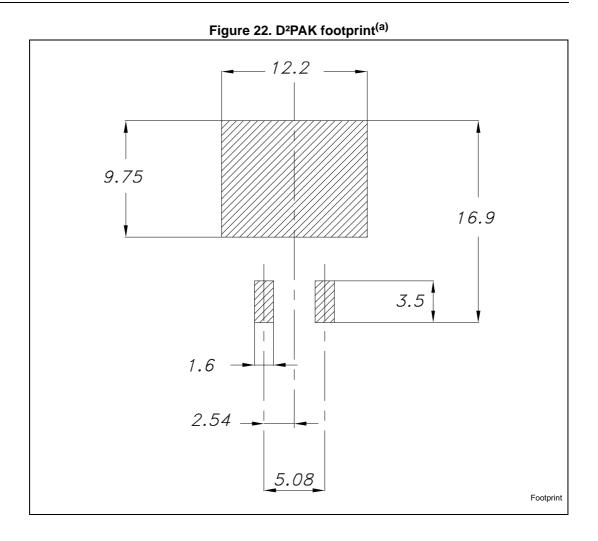
Figure 21. D²PAK (TO-263) type A package outline



Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
С	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
е		2.54	
e1	4.88		5.28
Н	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Table 9. D²PAK (TO-263) type A mechanical data



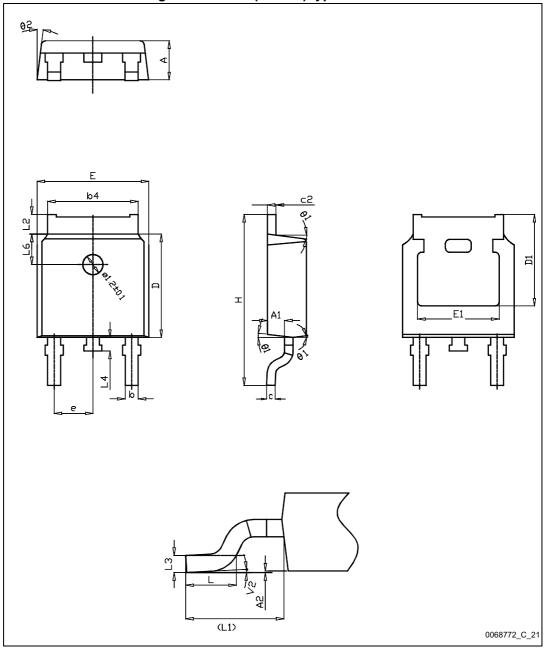


a. All dimension are in millimeters



4.2 DPAK(TO-252) package information

Figure 23. DPAK (TO-252) type C outline

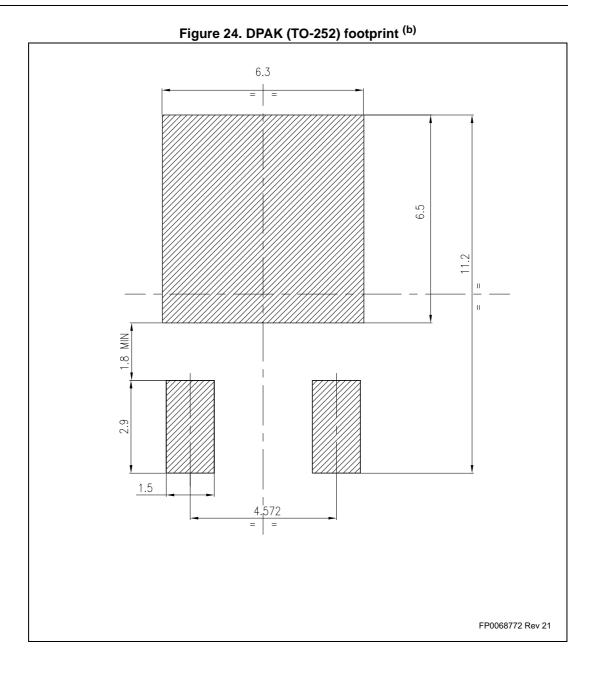




Dim. —	mm			
	Min.	Тур.	Max.	
A	2.20	2.30	2.38	
A1	0.90	1.01	1.10	
A2	0.00		0.10	
b	0.72		0.85	
b4	5.13	5.33	5.46	
С	0.47		0.60	
c2	0.47		0.60	
D	6.00	6.10	6.20	
D1	5.25			
E	6.50	6.60	6.70	
е	2.186	2.286	2.386	
E1	4.70			
Н	9.80	10.10	10.40	
L	1.40	1.50	1.70	
L1		2.90 REF		
L2	0.90		1.25	
L3		0.51 BSC		
L4	0.60	0.80	1.00	
L6		1.80 BSC		
Θ1	5°	7°	9°	
Θ2	5°	7°	9°	
V2	0°		8°	

Table 10. DPAK (TO-252) type C package mechanical data





b. All dimensions are in millimeters



5 Packing information

Таре				Reel		
Dim.	mm		Dim	mm		
	Min.	Max.	— Dim. —	Min.	Max.	
A0	10.5	10.7	А		330	
B0	15.7	15.9	В	1.5		
D	1.5	1.6	С	12.8	13.2	
D1	1.59	1.61	D	20.2		
Е	1.65	1.85	G	24.4	26.4	
F	11.4	11.6	N	100		
K0	4.8	5.0	Т		30.4	
P0	3.9	4.1				
P1	11.9	12.1	I	Base qty	1000	
P2	1.9	2.1		Bulk qty	1000	
R	50					
Т	0.25	0.35				
W	23.7	24.3				

Table 11. D²PAK (TO-263) tape and reel mechanical data



Таре				Reel		
Dim. —	mm		Dim	mm		
	Min.	Max.	— Dim	Min.	Max.	
A0	6.8	7	А		330	
B0	10.4	10.6	В	1.5		
B1		12.1	С	12.8	13.2	
D	1.5	1.6	D	20.2		
D1	1.5		G	16.4	18.4	
E	1.65	1.85	N	50		
F	7.4	7.6	Т		22.4	
K0	2.55	2.75				
P0	3.9	4.1		Base qty.	2500	
P1	7.9	8.1		Bulk qty.	2500	
P2	1.9	2.1				
R	40					
Т	0.25	0.35				
W	15.7	16.3				



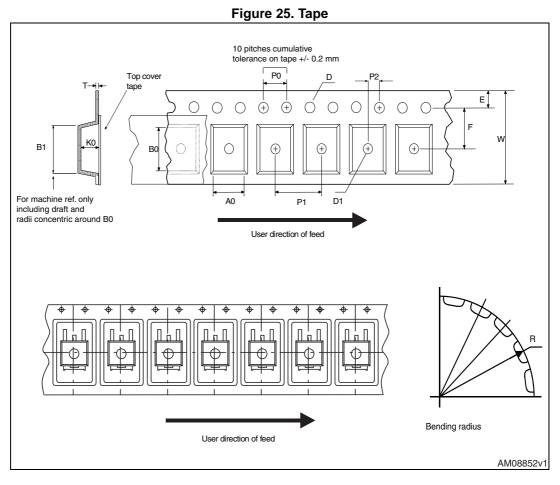
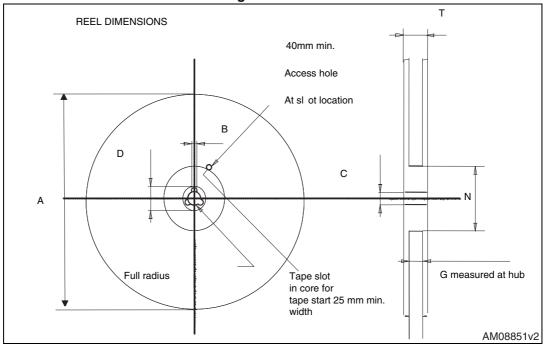


Figure 26. Reel





6 Revision history

Date	Revision	Changes	
11-Jun-2013	1	First release.	
09-Jul-2013	2 – Minor text changes – Modified: R _{thj-case} value for D ² PAK in table 3		
30-May-2016	3	Updated title, features and description. Updated <i>Table 6: Dynamic</i> and <i>Table 8: Source drain diode</i> . Updated <i>Section 4: Package information</i> and <i>Section 5: Packing information</i> . Minor text changes.	

Table 13. Document revision history



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